

**IN THE CLAIMS:**

Cancel Claims 2, 6-8, 10-11, and 13-14.

Claim 1 (currently amended)

1. A method of packaging a PVA sponge for use in scrubbing semiconductor wafers, said method comprising:

(a) placing said sponge in a flexible plastic bag;

(b) said sponge containing a quantity of de-ionized water with around 0.05% to [substantially less than 1%] around 0.5% by volume of hydrogen peroxide; and

(c) sealing said bag.

Claim 2 (previously withdrawn)

Claim 3 (previously amended)

3. A method as in Claim 1 in which said quantity of de-ionized water with hydrogen peroxide is between an amount sufficient to wet said sponge and an amount necessary to saturate said sponge.

Claim 4 (previously amended)

4. A method as in Claim 1 in which the volume of hydrogen peroxide is around 0.1%.

Claim 5 (currently amended)

5. A method of packaging a [cleaning article] PVA sponge brush, said method comprising placing said cleaning article in a plastic bag, said sponge brush containing a

quantity of de-ionized water, said water containing hydrogen peroxide in an amount effective to kill and retard the growth of bacteria in said cleaning article but less than an amount sufficient to develop significant quantities of metallic ions in said container, and sealing said container, in which said amount of hydrogen peroxide is about 0.05% to [substantially less than 1%] around 0.5% by volume.

Claim 6 (previously withdrawn)

Claim 7 (previously withdrawn)

Claim 8 (previously withdrawn)

Claim 9 (currently amended)

A packaged PVA sponge for use in clean rooms, said cleaning article having particulate, metal ion and anionic counts at or below the values specified for a clean room, said package comprising a sealed flexible plastic bag, said sponge being positioned in said bag, and containing a quantity of de-ionized water, said de-ionized water containing hydrogen peroxide in a concentration effective to kill and retard the growth of bacteria in said sponge, said amount being low enough to substantially ensure decomposition of said hydrogen peroxide in a relatively short period of time after the container is sealed and being between 0.05% and [substantially less than 1%] 0.5% by volume.

Claim 10 (previously withdrawn)

Claim 11 (previously withdrawn)

Claim 12 (previously amended)

12. A cleaning article as in Claim 9 in which said cleaning article is a PVA sponge for scrubbing semiconductor wafer surfaces, and said concentration of hydrogen peroxide is around 0.1 percent by volume.

Claim 13 (previously withdrawn)

Claim 14 (previously withdrawn)